

### IN THE CLAIMS

Please amend the claims as follows.

For the Examiner's convenience, a list of all claims is included below.

1. (Currently Amended) A thermal interface material, comprising:  
a binder material; and  
a fusible filler within the binder material, the fusible filler randomly positioned with respect to the binder material, wherein the fusible filler is selected from the group consisting of an indium alloy that includes silver in an approximate range of 1 to 20 percent by weight, a tin alloy that includes copper in an approximate range of 0.7 to 1.4 percent by weight, a tin alloy that includes silver in an approximate range of 1 to 5 percent by weight, a tin alloy that includes tin in an approximate range of 42 to 85 percent by weight and bismuth in an approximate range of 15 to 58 percent by weight, a tin alloy that includes silver in an approximate range of 3.0 to 4.0 percent by weight and copper in an approximate range of 0 to 1.7 percent by weight, a tin alloy that includes silver in an approximate range of 3 to 4 percent by weight and bismuth in an approximate range of 1 to 6 percent by weight, and a tin alloy that includes silver approximately 1 percent by weight and bismuth approximately 57 percent by weight ~~and forming columnar structures within the binder material, the columnar structures formed during a reflow process from a plurality of fusible filler particles such that a cross-sectional area of the columnar structures is greater than a cross-sectional area of the fusible filler particles;~~  
a plurality of non-fusible particles having a mean diameter of approximately 25 microns, within the binder material, the non-fusible particles randomly positioned with respect to the binder material, the fusible filler coated onto the non-fusible particles wherein a volume percent

of the fusible filler to non-fusible particles is in a range of approximately 10 – 50 percent by volume of fusible filler, wherein the non-fusible particles are selected from the group consisting of ceramic fiber, graphite fibers, carbon fibers, aluminum oxides, zinc oxide, graphite, carbon nanotubes, and silicon carbide.

2 - 5 (Canceled)

6. (Previously presented) The thermal interface material of claim 1, wherein the binder material is a polymer.

7. (Previously presented) The thermal interface material of claim 1, wherein the binder material acts as an adhesive.

8. (Canceled)

9. (Previously presented) The thermal interface material of claim 1, wherein the fusible filler is a solder alloy having a solidus temperature above 100° C.

10. (Canceled)

11. (Previously Presented) The thermal interface material of claim 1, wherein the fusible filler is 60 –95 % by weight of the total weight of the thermal interface material.

12 – 14 (Canceled)

15. (Previously presented) The thermal interface material of claim 1, wherein the fusible filler has a melting temperature of approximately between 100 - 250° C.

16. (Previously presented) The thermal interface material of claim 1, wherein the fusible filler is stable to oxygen at temperatures up to approximately 150° C and relative humidity up to approximately 90%.

17 - 26 (Canceled)

27. (Previously presented) The thermal interface material of claim 9, wherein the solder alloy has a solidus temperature below 250° C.

28-39 (Canceled)